

AI

1. (Amended) A conductor track supporting layer for laminating inside a chip card comprising at least one conductor track which is applied to a conductor track supporting layer by an application method, preferably a screen printing method, and consists of a conductive paste or high-viscosity liquid, and comprising connecting areas which are connected to the conductor track, characterized in that the conductor track supporting layer has in the region of the connecting areas indentations which are filled with the paste or the high-viscosity liquid during the application operation.

2. (Amended) The conductor track supporting layer as claimed in claim 1, wherein the indentations are made as through-holes with an opening on the rear side of the conductor track supporting layer, lying opposite the conductor track of the supporting layer.

3. (Amended) The conductor track supporting layer as claimed in claim 2, wherein it is provided on the rear side with a protective film.

4. (Amended) The conductor track supporting layer as claimed in claim 1, wherein the conductor track has the form and function of a coil.

5. (Amended) The conductor track supporting layer as claimed in claim 1, wherein the screen printing paste has a silver particle content of from 70 to 80% percent by volume.

6. (Amended) The conductor track supporting layer as claimed in claim 5, wherein the grain size of the silver particles is greater than 45 μm .

7. (Amended) The conductor track supporting layer as claimed in claim 1, wherein a plurality of sublayers provided with through-holes are stacked exactly in position one on top of the other and bonded to one another to form a common conductor track supporting layer, indentations of different depths being formed by making the positions of the through-holes in the sublayers coincide.

AI
cont.

8. (Amended) A chip card with a chip module, arranged in a recess of the chip card body, and/or further electronic components, with a conductor track supporting layer, to which at least conductor tracks comprising a screen printing paste and connecting areas connected to the conductor track have been applied by a screen printing method, characterized in that the conductor track supporting layer has in the region of the connecting areas indentations filled with screen printing paste, in that the recess for the chip module and/or further electronic components is arranged on the side of the conductor track supporting layer not coated with the conductor track and in that the recess has such a depth that the bottom region reaches so far into the conductor track supporting layer that the indentations filled with screen printing paste of the conductor track supporting layer are exposed.

2023-05-10 10:44:20

9. (Amended) A method for producing a chip card, comprising a multilayer plastic card body, at least one electronic component, preferably a chip module, arranged in a recess of the plastic card body, in which

at least one conductor track supporting layer, at least two covering layers covering the conductor track supporting layer on both flat sides are arranged exactly in position one on top of the other,

the card layers arranged one on top of the other are bonded to one another in a laminating press by the influence of pressure and heat,

after removal of the plastic card body from the laminating press, the recess for the electronic component (chip module) is milled into said body and

subsequently, the component for establishing an electrical connection with the connecting areas on the conductor track supporting layer is inserted into the recess of the plastic card body,

comprising

the making of indentations into the conductor track supporting layer at predetermined locations for the placement of connecting areas,

the coating of the conductor track supporting layer in an application method, preferably a screen printing method, with conductor tracks and connecting areas connected to the conductor tracks comprising screen printing paste in such a way that the paste or high-viscosity liquid used for the coating fills the indentations in the conductor track layer, the milling-out of the recesses for the electronic components

AI
cont.

from the outer side of the plastic card body, which is remote from the side of the conductor track supporting layer coated with conductor tracks, the recess having such a depth that its bottom region reaches into the conductor track supporting layer and the indentations filled with screen printing paste of the conductor track supporting layer are exposed.

10. (Amended) The method as claimed in claim 9, wherein the depressions are punched into the conductor track supporting layer as through-holes.

11. (Amended) The method as claimed in claim 10, wherein after the punching-out of the holes, the conductor track supporting layer is coated on one side with a protective film.

12. (Amended) The method as claimed in claim 9, wherein a plurality of sublayers provided with through-holes are stacked exactly in position one on top of the other and bonded to one another to form a common conductor track supporting layer, indentations of different depths being formed by making the positions of the through-holes in the sublayers coincide.
